

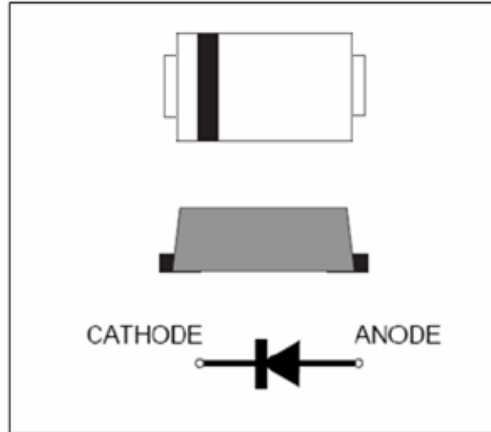
LMBR120ET1G thru LMBR1200ET1G

Schottky Barrier Rectifiers

Reverse Voltage 20 to 200V Forward Current 1.0A

FEATURES

- * Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- * Low power loss,high efficiency
- * For use in low voltage high frequency inverters, free wheeling,and polarity protection applications
- * Guardring for over voltage protection
- * High temperature soldering guaranteed: 260°C/10 seconds at terminals



We declare that the material of product is Halogen free (green epoxy compound)

Mechanical Data

Case: SOD-323HE

molded plastic over sky die

Terminals: Tin Plated, solderable per

MIL-STD-750, Method 2026

Polarity: Color band denotes cathode end

Mounting Position Any

Weight: 0.0053 g

Handling precautinNone

1.Electrical Characteristic

Maximum & Thermal Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

Parameter Symbol	symbol	LMBR 120ET1G	LMBR 130ET1G	LMBR 140ET1G	LMBR 150ET1G	LMBR 160ET1G	LMBR 180ET1G	LMBR 1100ET1G	LMBR 1150ET1G	LMBR 1200ET1G	Unit	
device marking code		12	13	14	15	16	18	110	115	120		
Maximum repetitive peak reverse voltage	V_{RRM}	20	30	40	50	60	80	100	150	200	V	
Maximum RMS voltage	V_{RMS}	14	21	28	35	42	56	70	105	140	V	
Maximum DC blocking voltage	V_{DC}	20	30	40	50	60	80	100	150	200	V	
Maximum average forward rectified current at $T_c = 75^\circ C$	$I_{F(AV)}$	1.0									A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	22									A	
Typical thermal resistance (Note 1)	$R_{\theta JA}$ $R_{\theta JL}$	220 50										$^\circ C/W$
Operating junction temperature range	T_J	-55 to +125				-55 to +150					$^\circ C$	
storage temperature range	T_{STG}	-55 to +150									$^\circ C$	

Electrical Characteristics Ratings at 25°C ambient temperature unless otherwise specified.

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Maximum instantaneous forward voltage at($I_F = 0.7 A, T_J = 25^\circ C$) ($I_F = 1.0 A, T_J = 25^\circ C$)	V_F	0.48 0.55			0.68		0.85		0.9	0.92	V
Maximum DC reverse current at rated DC blocking voltage $T_A = 25^\circ C$ $T_J = 125^\circ C$	I_R	0.25 10	0.13 10	0.03 10							mA
Typical junction capacitance at 4.0V, 1MHz	C_J	160									PF

NOTES:

1. 8.0mm² (.013mm thick) land areas

LMBR120ET1G thru LMBR1200ET1G

2. Ratings and Characteristic Curves (TA = 25°C unless otherwise noted)

Fig. 1 - Forward Current Derating Curve Fig. 2 - Maximum Non-repetitive Peak Forward Surge Current

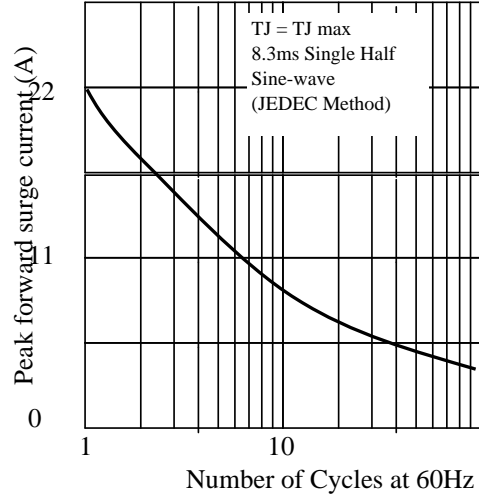
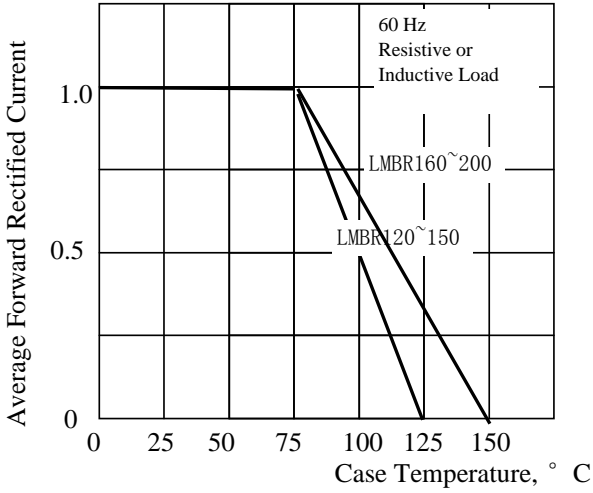


Fig. 3 - Typical Instantaneous Forward Characteristics

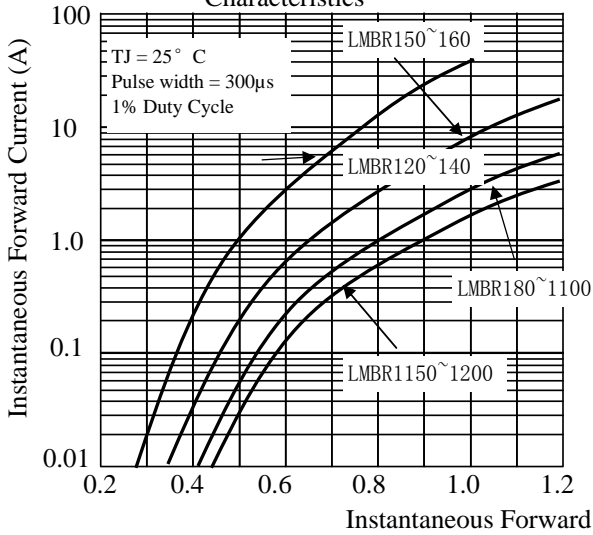


Fig. 4 - Typical Reverse Characteristics

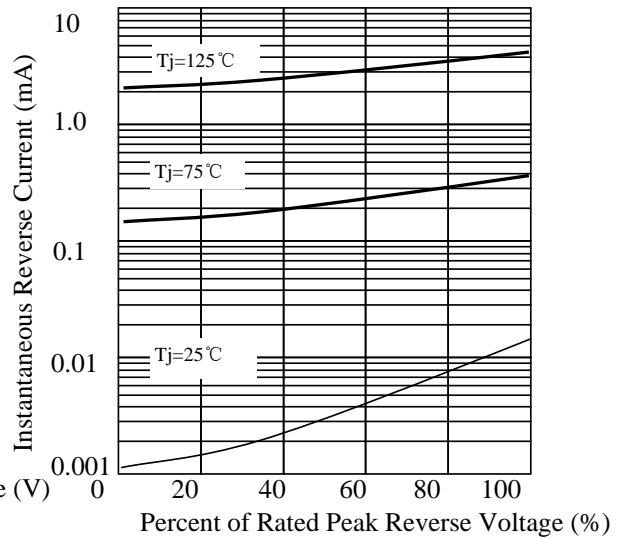


Fig. 5 - typical transient thermal impedance

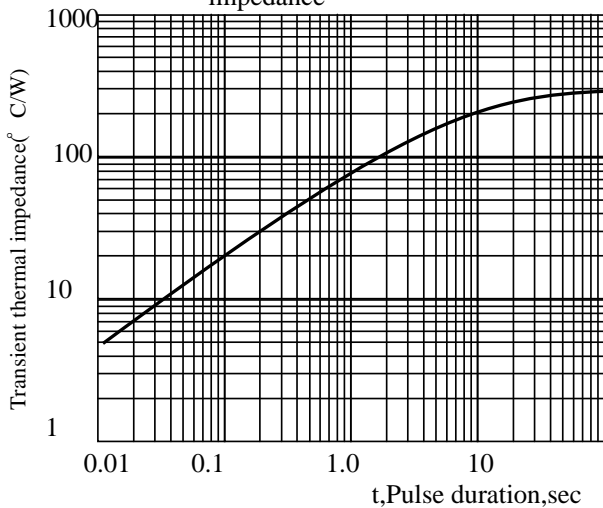
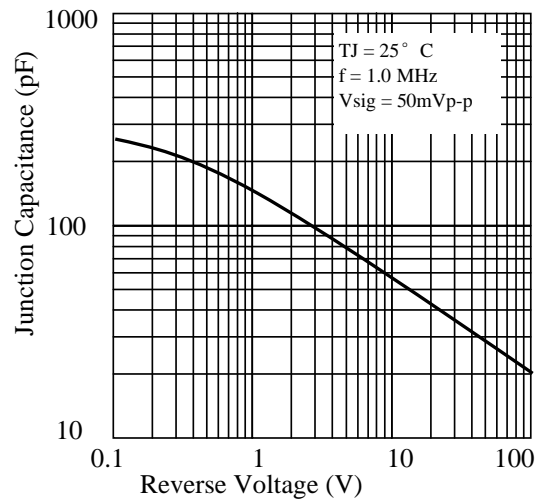
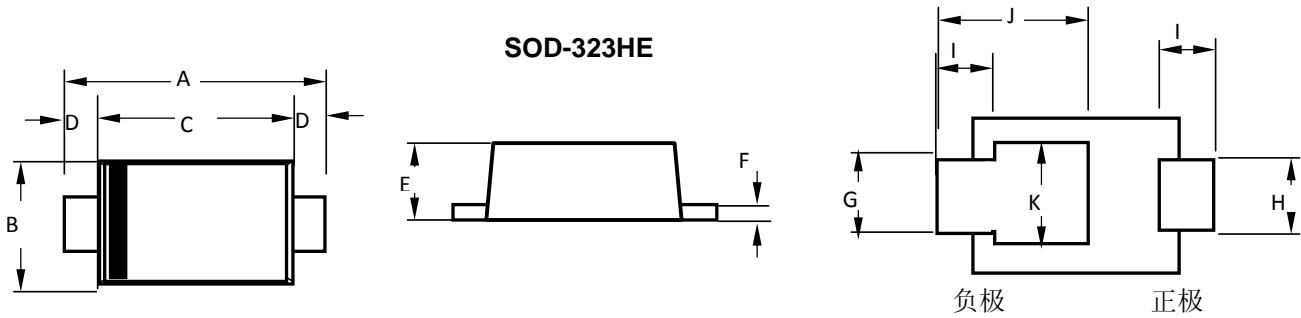


Fig. 6 - Typical Junction Capacitance



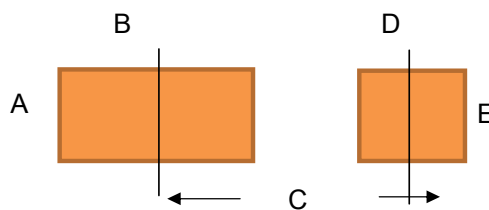
LMBR120ET1G thru LMBR1200ET1G

3. dimension:



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.30	2.70	0.091	0.106
B	1.20	1.35	0.047	0.053
C	1.75	1.95	0.069	0.077
D	0.30Typ		0.012Typ	
E	0.55	0.75	0.022	0.030
F	0.10	0.20	0.004	0.008
G	0.50	0.55	0.020	0.022
H	0.50	0.55	0.020	0.022
I	0.40	0.60	0.016	0.024
J	1.15	1.55	0.045	0.061
K	0.8Typ		0.032Typ	

Suggested solder pad layout



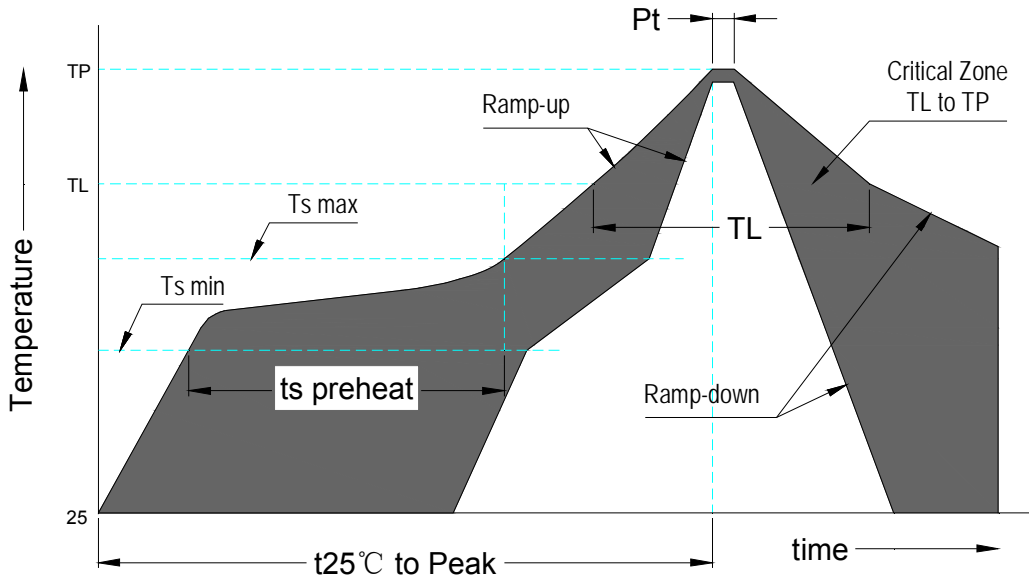
Dimensions in inches and (millimeters)

PACKAGE	A	B	C	D	E
SOD323-HE	0.043(1.1)	0.079(2.0)	0.078(1.9)	0.031(0.8)	0.039(1.0)

LMBR120ET1G thru LMBR1200ET1G

5. Suggested thermal profile for soldering process

1. Storage environment : Temperature=5~40°C Humidity=55±25%
2. Reflow soldering of surface-mount device



3. Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat	
- Temperature Min(T_{smin})	150°C
- Temperature Max(T_{smax})	200°C
- Time(min to max)(t_s)	60~120sec
T_{smax} to T_L	
- Ramp-up Rate	<3sec
Time maintained above:	
- Temperature (T_L)	217°C
- Time(t_L)	60-260sec
Peak Temperature(T_P)	255 -0/+5°C
Time within 5°C of actual Peak Temperature(T_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes

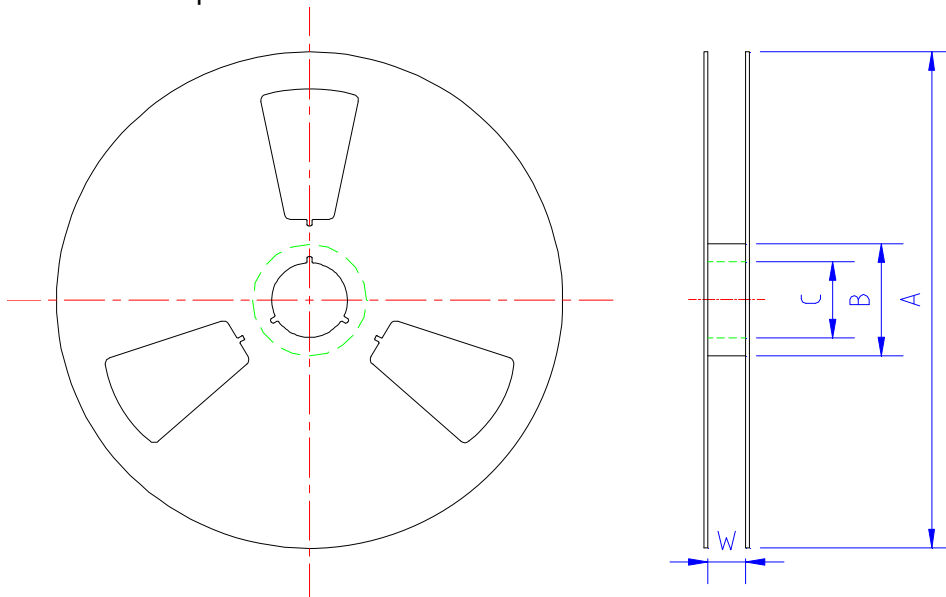
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6.High reliability test capabilities

Item Test	Condition	Reference
Solder Resistance	at 260±5°C for 10±2sec immerse	MIL-STD-750D METHOD-2031
Solderability	at 245±5°C for 5 sec	MIL-STD-202F METHOD-208
High Temperature Reverse Bias	V _R =80% rate at T _j =125°C for 168hrs	MIL-STD-750D METHOD-1038
Forward Operation Life	Rated average rectifier current	MIL-STD-750D METHOD-1027
Intermittent Operation Life	T _A =25°C , I _F =I _O	MIL-STD-750D METHOD-1036
Pressure Cooker	15P _{SIG} at T _A =121°C for 4hrs	JESD22-A102
Temperature Cycling	-55°C to +125°C dwelled for 30 min. and transferred for 5min. Total 10 cycles	MIL-STD-750D METHOD-1051
Thermal Shock	0°C for 5min. Rise to 100°C for 5min. Total 10 cycles	MIL-STD-750D METHOD-1056
Forward Surge	8.3ms single half sine-wave superimposed on rated load,one surge	MIL-STD-750D METHOD-4066-2
Humidity	at T _A =85°C , RH=85% for 1000hrs	MIL-STD-750D METHOD-1021
High Temperature Storage Life	at 150°C for 1000hrs	MIL-STD-750D METHOD-1031

5.1 、 SMD Packing Reel Spec & Packing Quantity

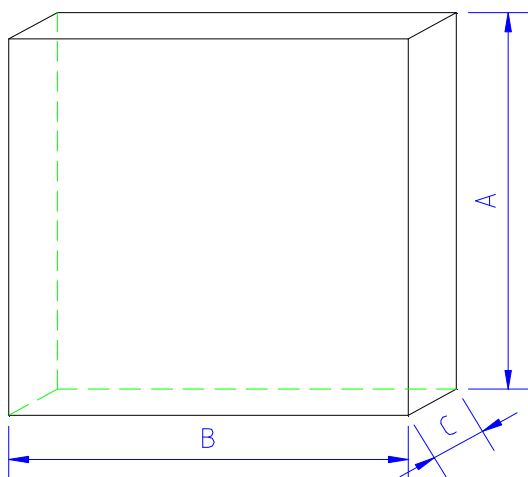
5.1.1 Reel Packing
A. Reel Spec



unit: mm

SPEC	A	B	C	W	Quantity/Reel
SMA-FL 7" reel	177.0±2.0	54.0±0.5	13.0±0.5	13.2±0.2	3K
TO277 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K
SOD123FL 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SOD323HE 7" reel	177.0±2.0	50.0±0.5	13.0±0.5	9.4±1.5	3K
SMB-FL 13" reel	330.0±2.0	75.0±0.5	13.0±0.5	13.2±0.2	5K

B. 13" reel packing box



unit: mm

size	A	B	C
	335±5.0	335±2.0	40±1.0

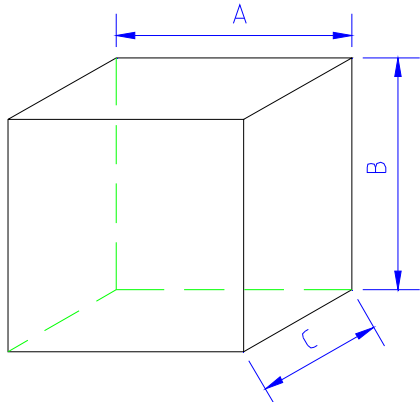
as per above packing

Spec	Q' ty/Box
TO277 13" reel	10K
SMB-FL 13" reel	10K

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C. 7" reel packing box



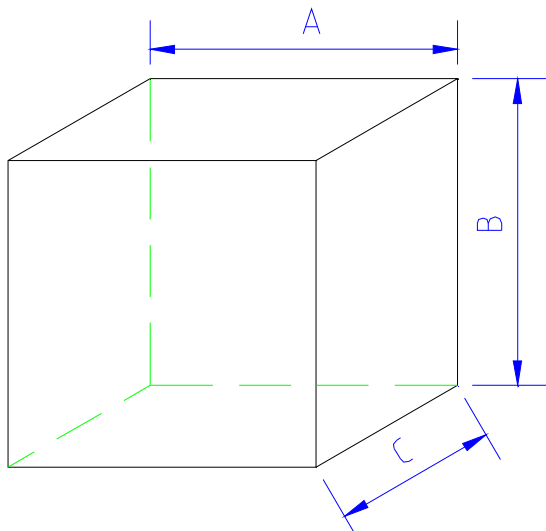
unit: mm

	A	B	C
SMA-FL SOD123FL SOD323HE	186±2.0	139±2.0	185±2.0

as per above packing

	Q' ty/Box
SMA-FL	30K
SOD123FL	30K
SOD323HE	30K

D. reel packing carton



unit: mm

	A	B	C
size	350±2.0	340±2.0	350±2.0

as per above packing

Spec	Q' ty/Carton
TO277 13" reel	80K
SMB-FL 13" reel	80K

unit: mm

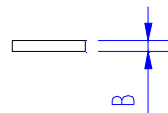
	A	B	C
SMA-FL SOD123FL SOD323HE	455±2.0	400±2.0	410±2.0

as per above packing

Spec	Q' ty/Carton
SMA-FL 7" reel	360K
SOD123-FL 7" reel	360K
SOD323HE 7" reel	360K

5.1.2 Tape Spec

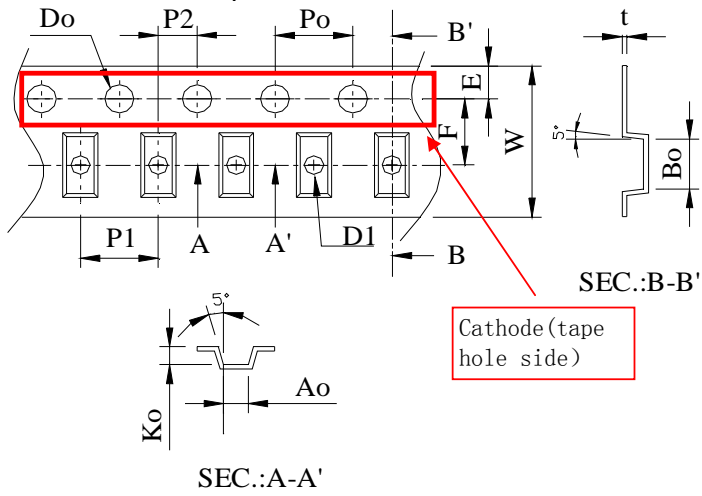
A. Cover Tape



unit: mm

	A	B
SMA-FL SMB-FL TO277	9.5±0.10	0.062±0.007
SOD123FL SOD323HE	5.4±0.10	

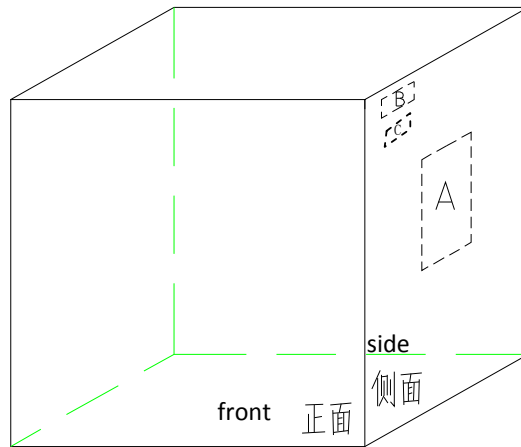
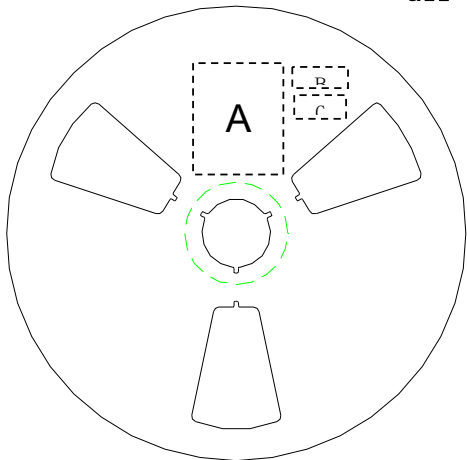
B. Carrier Tape



Item	SOD323HE	SOD123FL	SMA-FL	SMB-FL	TO277
W	8±0.3	8±0.3	12±0.3	12±0.3	12±0.3
P1	4±0.1	4±0.1	4±0.1	8±0.1	8±0.1
E	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1	1.75±0.1
F	3.5±0.05	3.5±0.05	5.5±0.05	5.5±0.05	5.5±0.05
D0	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05	1.55±0.05
D1	1.1±0.1	1.1±0.1	1.5±0.1	1.55±0.05	1.5±0.1
P0	4±0.1	4±0.1	4±0.1	4±0.1	4±0.1
P2	2±0.05	2±0.05	2±0.05	2±0.05	2±0.05
10P0	40±0.2	40±0.2	40±0.2	40±0.2	40±0.2
A0	1.45±0.1	1.95±0.1	2.83±0.1	3.8±0.1	4.3±0.1
B0	2.75±0.1	3.95±0.1	4.75±0.1	5.75±0.1	6.8±0.1
K0	0.80±0.1	1.30±0.1	1.42±0.1	1.4±0.1	1.35±0.1
T	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05	0.25±0.05

5.2、SMD Power Diode General Packing Spec

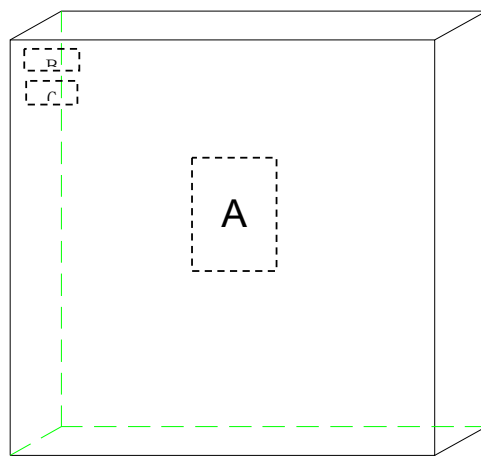
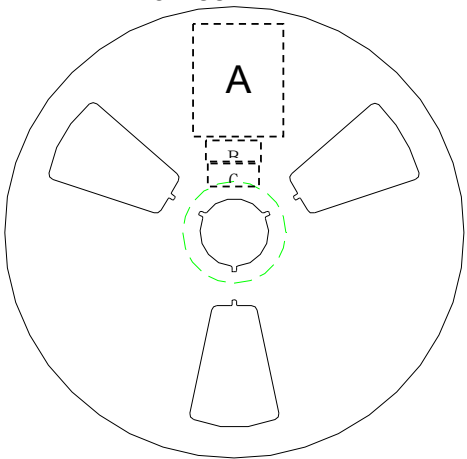
A. 7" reel all labels will be at cathode side of reel ;



A:LRC label;

B:Environment Label C:Halide free label

B. 13" reel



A:LRC label;

B:Environment Label C:Halide free label

C. Tape lead: face anode side of the reel, upper side is the tape lead position. All labels are at cathode side of the reel.

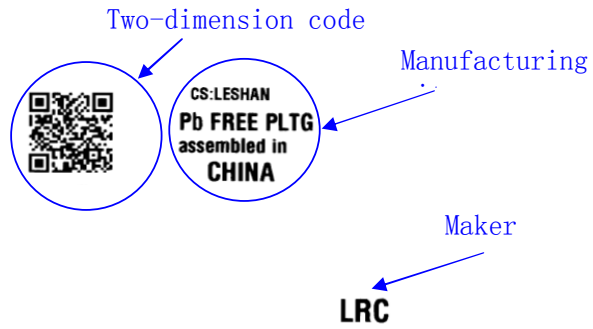


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User Direction of Feed

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C. Label Content :
LRC Label

P/N → (1P) LPN: **SM140A**
 Lot No. → (1T) LOT: **140106049X**
 Date code → (9D) DTE: **1403**
 Quantity → (Q) QTY: **10000**



lot: 140106049X: 140106---2014/1/6; 049----lot number:49; X: product code

Environment Label



Halide-free Label



LMBR120ET1G thru LMBR1200ET1G

7. Update Record

版次	更新记录	更新作者	更新日期
1	第一版	周杰	2014.02.26
2	修正产品引脚G尺寸, 由0.75~0.95mm为0.50~0.55mm	周杰	2014.07.18
3	修正60~200V产品的TJ为150℃	周杰	2014.08.08
4	修正修正焊盘尺寸	周杰	2014.10.09